

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	6	(dog adj bone or dogbone) near2 capacitor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/09 13:17
L4	220	(surface near mount\$2 or chip or mounted or mounting or decoupling or smt or smd) near2 (capacitor or resistor or diode or inductor) and (chip or die or ic) near4 (underfill\$3 or under-fill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/09 13:19
L5	10	("5817545"   "6071371"   "6100597"   "6214635"   "6214642"   "6242513"   "6268739"   "6271058"   "6306688"   "6399178"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/09 14:25
L6	20	("4627988"   "4798694"   "4906314"   "5126085"   "5128380"   "5169911"   "5220724"   "5268048"   "5286679"   "5296559"   "5348607"   "5350811"   "5475048"   "5554684"   "5579573"   "5627108"   "5668059"   "5677246"   "5846851"   "6238223"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/09 15:06
L9	19	(US-20010023983-\$ or US-20020062970-\$ or US-20020131253-\$ or US-20030075805-\$ or US-20030080437-\$ or US-20040040740-\$ or US-20030171456-\$ or US-20030170450-\$ or US-20020035201-\$).did. or (US-5493259-\$ or US-5529957-\$ or US-6011683-\$ or US-6018192-\$ or US-6409070-\$ or US-6459561-\$ or US-6727119-\$ or US-6555414-\$ or US-6440777-\$ or US-6399178-\$).did.	US-PGPUB; USPAT	OR	ON	2005/06/09 15:11
L10	15	("5493259").URPN.	USPAT	OR	ON	2005/06/09 15:20
S1	17	(passive near3 device or smd or resistor or capacitor or diode) near6 (bonded or flip adj chip or mounted or mount) near10 (noflow or no-flow or reflow or preform or preformed) near6 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/09 13:09
S2	454	(passive near3 device or smd or resistor or capacitor or diode) near15 (noflow or no-flow or reflow or preform or preformed or strip) near6 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/03 15:49
S4	188	(passive near3 device or smd or resistor or capacitor or diode) near10 (noflow or no-flow or reflow or preform or preformed or strip) near3 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/03 15:49
S5	18	("20020190370"   "20030049411"   "20030080437"   "4339785"   "5085364"   "5128746"   "5493259"   "5528461"   "5529957"   "5814401"   "6013571"   "6071371"   "6202917"   "6234379"   "6458472"   "6475828"   "6489180"   "6578755").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 15:58
S6	343	surface near mount near capacitor	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 15:58
S7	48	surface near mount near capacitor same (encapsulant or encapsulation or encapsulating or resin or epoxy or underfill or underfilling or under-fill or molding or adhesive)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 16:12
S8	11	("3991347"   "4126840"   "4139881"   "4164778"   "4339785"   "4578737"   "4617586"   "4761881"   "4814943"   "5034710"   "5082457").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 16:05
S9	15	("5493259").URPN.	USPAT	OR	ON	2005/06/03 16:06
S10	9	(smt or smd) near capacitor same (encapsulant or encapsulation or encapsulating or resin or epoxy or underfill or underfilling or under-fill or molding or adhesive)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 16:14

S11	1460	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 16:15
S12	51	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer) same (noflow or no-flow or reflow or preform or preformed or pre-form or underfill or underfilling)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 16:48
S13	108	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer or substrate) same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 17:11
S14	268	(chip or die) adj capacitor same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 17:15
S15	6	(chip or die) near capacitor same (noflow or no-flow or reflow or preform or preformed) near6 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/03 17:14
S16	27	capacitor near5 (underfill or underfilling or underfilled or under-fill or under-filling or under-filled)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:00
S17	12	("4439813"   "5175609"   "5266522"   "5471092"   "5903058"   "6043973"   "6071800"   "6121127"   "6121688"   "6222246"   "6222260"   "6235412").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 17:07
S18	15	("4788767"   "5371404"   "5777847"   "5796170"   "5811317"   "5866943"   "5879786"   "5895967"   "5955789"   "6020221"   "6051888"   "6144101"   "6313521"   "6437436"   "6504096").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 17:08
S19	51	(passive near3 device or smd or resistor or capacitor or diode) near6 (underfill\$3 or under-fill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/09 10:58
S20	9	("2085587"   "4294395"   "4568277"   "4580716"   "4855007"   "5085364"   "5531372"   "6238487").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/09 11:08
S21	14	("5085364").URPN.	USPAT	OR	ON	2005/06/09 11:09
S22	4	("4749120"   "4851966"   "4979663"   "5012969").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/09 11:15
S23	50	chip near capacitor near4 (underfill\$3 or under-fill\$3 or no-flow or noflow or preform\$3 or encapsula\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/09 11:26
S24	10	(chip near capacitor or passive near capacitor or surface near mount\$3 near capacitor or bga near5 capacitor) near4 (underfill\$3 or under-fill\$3 or no-flow or noflow or preform\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/09 11:35
S25	19	(chip near capacitor or passive near capacitor or surface near mount\$3 near capacitor or bga near5 capacitor) near10 (underfill\$3 or under-fill\$3 or no-flow or noflow or preform\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/09 11:35

S26	4	("6207475"   "6391682"   "6391683"   "6498054").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/09 11:37
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